[IV~27]

Extraction Efficiency of Cu Ion on CZ Si Surface by Scanning Solution

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It is well known that micro contamination analysis of CZ Si wafer surface is essential to obtain good device yield and reliability. Scanning solution used to analize the Si wafer surface contaminated by Cu was HF, HNO_3:HF(mixed acid 1), HNO_3:HF(mixed acid 2, HNO_3 rich) and HF+H_2O_2. To evaluate scanning extraction efficiency of each scanning solution, TRXRF and AAS were used. The order of scanning extraction efficiency was HF+H_2O_2 > HNO_3:HF(mixed acid 1) ≥ HNO_3:HF(mixed acid 2, HNO_3 rich) > 1% HF.

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